

15A, 25A, 35A, 50V - 1000V Standard Bridge Rectifier

FEATURES

- Glass passivated chip junction
- Integrally molded heatsink provide very low thermal resistance for maximum heat dissipation
- Typical I_R less than 0.2μA
- High surge current capability
- UL Recognized File # E-326243
- RoHS Compliant

ΛЕ	ы	.ICA	\mathbf{O} N	c
МГ	TL		 UI	3

- Switching mode power supply (SMPS)
- AC to DC converter

MECHANICAL DATA

· Case: GBPC

GBPC-W: Wire structure

GBPC40-M: Terminal cathode parallel to anode

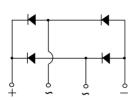
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Mounting torque: 20 in-lbs maximum
- Polarity: As marked
- Weight: 16.95g (approximately)

KEY PARAMETERS						
PARAMETER	VALUE	TINU				
I _F	15, 25, 35	Α				
V_{RRM}	50 - 1000	V				
I _{FSM}	300, 400	Α				
T _{J MAX}	150	°C				
Package	GBPC					
Configuration	Quad					









GBPC-M

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)										
PARAMETER		SYMBOL	005	01	02	04	06	08	10	UNIT
Repetitive peak reverse voltage		V_{RRM}	50	100	200	400	600	800	1000	V
Reverse voltage, total rms val	ue	V _{R(RMS)}	35	70	140	280	420	560	700	V
GBPC15						15				Α
Forward current	GBPC25	I _F	25						Α	
	GBPC35		35						Α	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load GBPC38		I _{FSM}	300					А		
		1 OW	400						Α	
Rating for fusing (t<8.3ms) GBPC15 GBPC25		l ² t	373						A ² s	
reaming for reaming (creating)	GBPC35		664						A ² s	
Junction temperature		TJ	- 55 to +150					°C		
Storage temperature		T _{STG}	- 55 to +150				°C			

THERMAL PERFORMANCE							
PARAMETER	SYMBOL	TYP	UNIT				
Junction-to-case thermal resistance	R _{eJC}	1.5	°C/W				

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)								
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT		
Forward voltage per diode ⁽¹⁾	GBPC15	I _F = 7.5A, T _J = 25°C	V _F	-	1.1	V		
	GBPC25	I _F = 12.5A, T _J = 25°C		-	1.1	V		
	GBPC35	I _F = 17.5A, T _J = 25°C		-	1.1	V		
Reverse current @ rated V _R per diode ⁽²⁾		T _J = 25°C	I _R	-	5	μA		

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

DERING INFORMATION						
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING				
GBPC*x	GBPC	50 / Tray				
GBPC*xM	GBPC-M	50 / Tray				
GBPC*xW	GBPC-W	50 / Tray				

Notes:

1. "*" defines current from 15A (GBPC15x/GBPC15xM/GBPC15xW) to 35A (GBPC35x/GBPC35xM/GBPC35xW), "x" defines voltage from 50V(GBPC*005/GBPC*005M/GBPC*005W) to 1000V(GBPC*10/GBPC*10M/ GBPC*10W)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

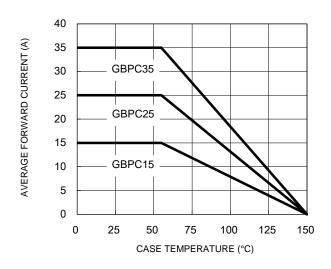


Fig.3 Typical Reverse Characteristics

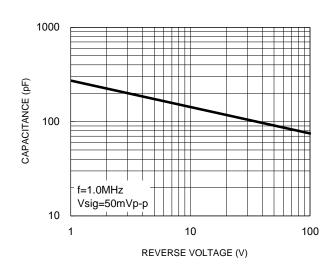
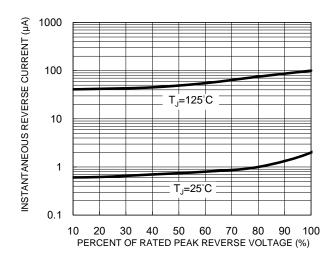


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



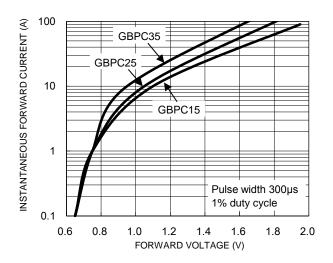
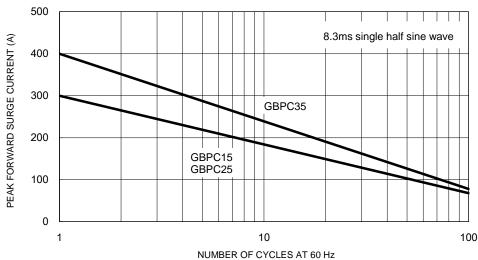
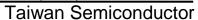


Fig.5 Maximum Non-Repetitive Forward Surge Current

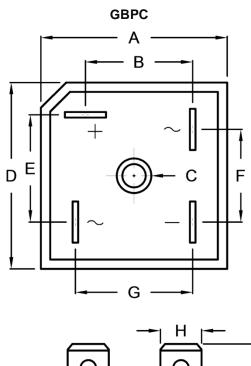


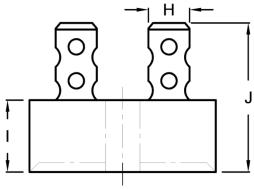
3





PACKAGE OUTLINE DIMENSIONS



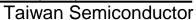


DIM.	Unit	(mm)	Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	28.50	29.00	1.122	1.142	
В	15.50	17.60	0.610	0.693	
С	5.08	5.59	0.200	0.220	
D	28.50	29.00	1.122	1.142	
E	15.50	17.60	0.610	0.693	
F	13.30	15.30	0.524	0.602	
G	17.10	19.10	0.673	0.752	
Н	6.35 (TYP.)		0.250	(TYP.)	
Ī	10.97	11.23	0.432	0.442	
J	21.50	24.50	0.846	0.965	

MARKING DIAGRAM

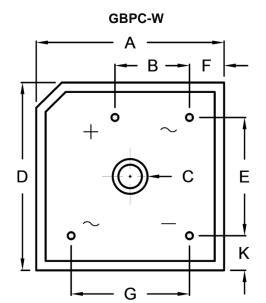


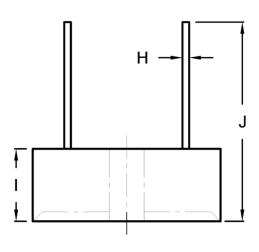
P/N = Marking Code YWW = Date Code F = Factory Code





PACKAGE OUTLINE DIMENSIONS





DIM.	Unit	(mm)	Unit (inch)		
	Min.	Max.	Min.	Max.	
Α	28.50	29.00	1.122	1.142	
В	10.40	12.40	0.409	0.488	
С	5.08	5.59	0.200	0.220	
D	28.50	29.00	1.122	1.142	
E	17.10	19.10	0.673	0.752	
F	4.40	6.20	0.173	0.244	
G	17.10	19.10	0.673	0.752	
Н	0.97	1.07	0.038	0.042	
I	10.97	11.23	0.432	0.442	
J	30.50	-	1.201	-	
K	4.40	6.20	0.173	0.244	

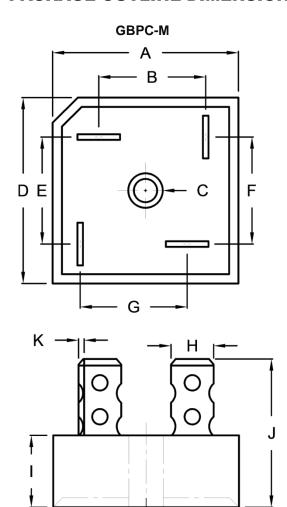
MARKING DIAGRAM



P/N = Marking Code YWW = Date Code F = Factory Code



PACKAGE OUTLINE DIMENSIONS



DIM.	Unit	(mm)	Unit (inch)		
	Min.	Max.	Min.	Max.	
Α	28.50	29.00	1.122	1.142	
В	15.50	17.60	0.610	0.693	
С	5.08	5.59	0.200	0.220	
D	28.50	29.00	1.122	1.142	
E	15.50	17.60	0.610	0.693	
F	15.50	17.60	0.610	0.693	
G	15.50	17.60	0.610	0.693	
Н	6.60	(TYP.)	0.260 (TYP.)		
ı	10.97	11.23	0.432	0.442	
J	21.26	24.57	0.837	0.967	
К	0.76	0.86	0.030	0.034	

MARKING DIAGRAM



P/N = Marking Code YWW = Date Code F = Factory Code

Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale..